

ABSTRACT

TEMPERATURE CONTROL OF A BONDING STAGE

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A bonding apparatus is provided comprising a bonding stage for holding a bonding tool, an air distribution system mounted to the bonding stage and an air inlet attached to the air distribution system. The air distribution system is connected to the air inlet for receiving air from the air inlet, and is operative to
10 pass the air over multiple surfaces of the bonding stage for the purpose of temperature control.

(FIG. 7)